

# LH534P00A

CMOS 4M (512K × 8/256K × 16)  
Mask-Programmable ROM

## FEATURES

- 524,288 words × 8 bit organization (Byte mode)  
262,144 words × 16 bit organization (Word mode)
- Access time: 120 ns (MAX.)
- Power consumption:  
Operating: 357.5 mW (MAX.)  
Standby: 550 μW (MAX.)
- Static operation
- TTL compatible I/O
- Three-state outputs
- Single +5 V power supply
- Packages:
  - 40-pin, 600-mil DIP
  - 40-pin, 525-mil SOP
  - 48-pin, 12 × 18 mm<sup>2</sup> TSOP (Type I)

## DESCRIPTION

The LH534P00A is a 4M-bit mask-programmable ROM organized as 524,288 × 8 bits (Byte mode) or 262,144 × 16 bits (Word mode) that can be selected by  $\overline{\text{BYTE}}$  input pin. It is fabricated using silicon-gate CMOS process technology.

## PIN CONNECTIONS

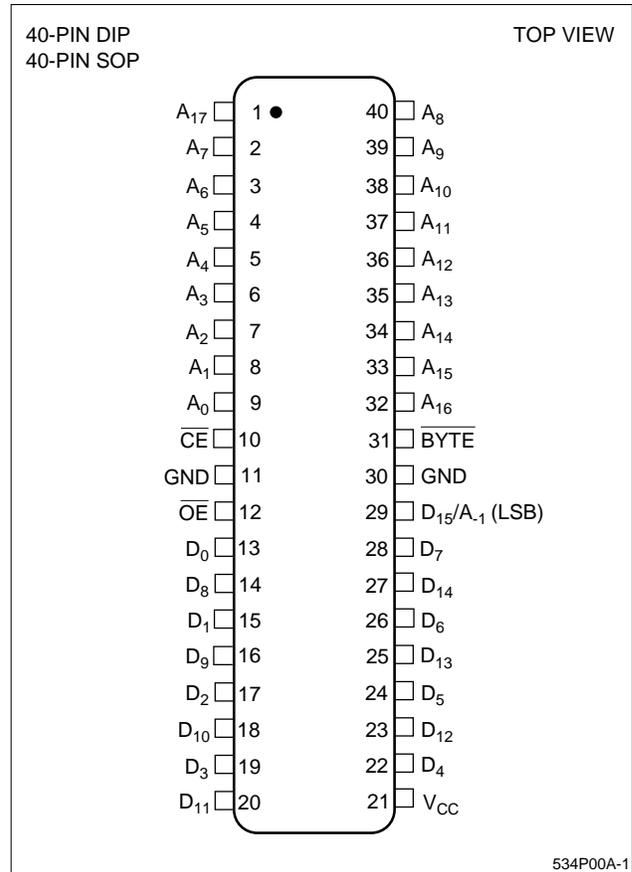
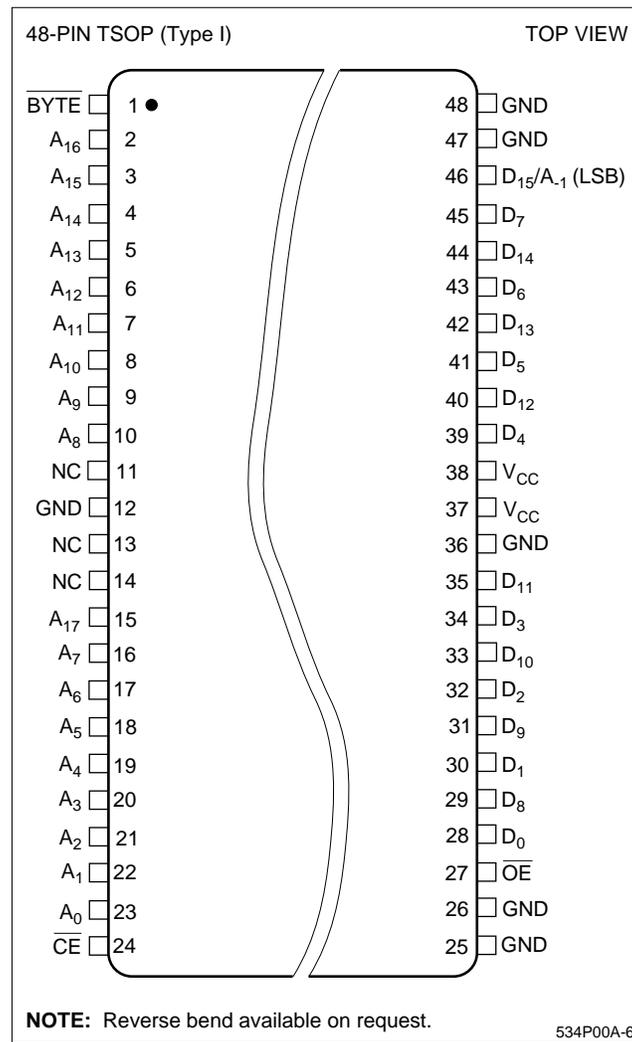


Figure 1. Pin Connections for DIP and SOP Packages



**Figure 2. Pin Connections for TSOP Package**

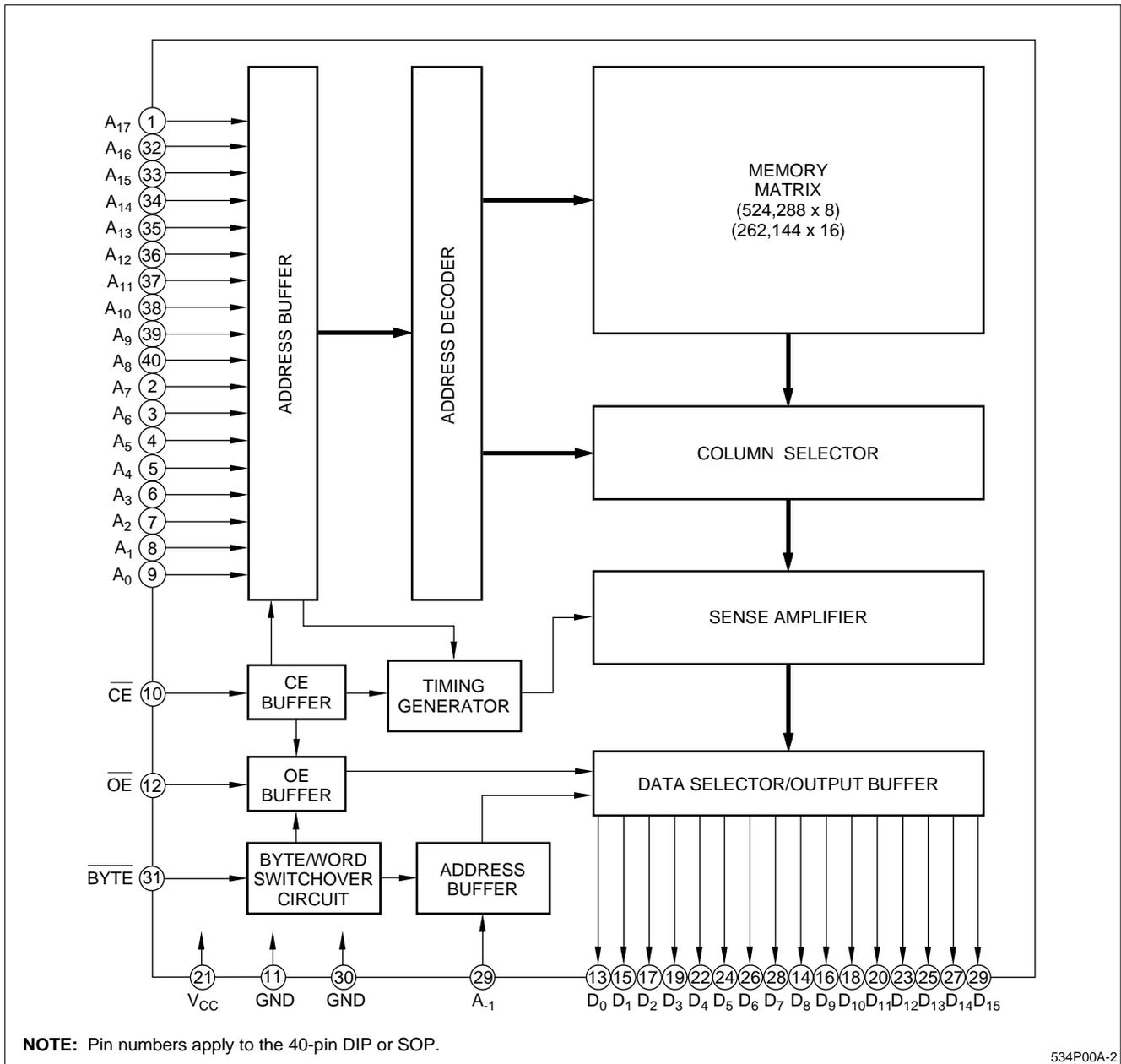


Figure 3. LH534P00A Block Diagram

**PIN DESCRIPTION**

SIGNAL	PIN NAME	NOTE
A <sub>-1</sub>	Address input (BYTE mode)	1
A <sub>0</sub> – A <sub>17</sub>	Address input	
D <sub>0</sub> – D <sub>15</sub>	Data output	1
BYTE	Byte/word mode switch	1

SIGNAL	PIN NAME	NOTE
CE	Chip enable input	
OE	Output enable input	
V <sub>CC</sub>	Power supply (+5 V)	
GND	Ground	

**NOTE:**

- D<sub>15</sub>/A<sub>-1</sub> pin becomes LSB address input (A<sub>-1</sub>) when the bit configuration is set in byte mode, and data output (D<sub>15</sub>) when in word mode. BYTE input pin selects bit configuration.

## TRUTH TABLE

$\overline{CE}$	$\overline{OE}$	$\overline{BYTE}$	A-1	MODE	DATA OUTPUT		SUPPLY CURRENT	NOTE
					D <sub>0</sub> – D <sub>7</sub>	D <sub>8</sub> – D <sub>15</sub>		
H	X	X	X	Not selected	High-Z	High-Z	Standby (I <sub>SB</sub> )	1
L	H	X	X	Not selected	High-Z	High-Z	Operating (I <sub>CC</sub> )	
L	L	H	Input inhibit	Word	D <sub>0</sub> – D <sub>7</sub>	D <sub>8</sub> – D <sub>15</sub>	Operating (I <sub>CC</sub> )	
L	L	L	L	Byte	D <sub>0</sub> – D <sub>7</sub>	High-Z	Operating (I <sub>CC</sub> )	
L	L	L	H	Byte	D <sub>8</sub> – D <sub>15</sub>	High-Z	Operating (I <sub>CC</sub> )	

## NOTE:

- The input state of  $\overline{BYTE}$  pin must not be changed during operation. The  $\overline{BYTE}$  pin must be set to either HIGH or LOW.  
X = H or L

## ABSOLUTE MAXIMUM RATINGS

PARAMETER	SYMBOL	RATING	UNIT
Supply voltage	V <sub>CC</sub>	–0.3 to +7.0	V
Input voltage	V <sub>IN</sub>	–0.3 to V <sub>CC</sub> + 0.3	V
Output voltage	V <sub>OUT</sub>	–0.3 to V <sub>CC</sub> + 0.3	V
Operating temperature	T <sub>opr</sub>	0 to +70	°C
Storage temperature	T <sub>stg</sub>	–65 to +150	°C

RECOMMENDED OPERATING CONDITIONS (T<sub>A</sub> = 0 to +70°C)

PARAMETER	SYMBOL	MIN.	TYP.	MAX.	UNIT
Supply voltage	V <sub>CC</sub>	4.5	5.0	5.5	V

DC CHARACTERISTICS (V<sub>CC</sub> = 5 V ±10%, T<sub>A</sub> = 0 to +70°C)

PARAMETER	SYMBOL	CONDITIONS	MIN.	TYP.	MAX.	UNIT	NOTE
Input 'Low' voltage	V <sub>IL</sub>		–0.3		0.8	V	
Input 'High' voltage	V <sub>IH</sub>		2.2		V <sub>CC</sub> + 0.3	V	
Output 'Low' voltage	V <sub>OL</sub>	I <sub>OL</sub> = 2.0 mA			0.4	V	
Output 'High' voltage	V <sub>OH</sub>	I <sub>OH</sub> = –400 μA	2.4			V	
Input leakage current	I <sub>LI</sub>	V <sub>IN</sub> = 0 V to V <sub>CC</sub>			10	μA	
Output leakage current	I <sub>LO</sub>	V <sub>OUT</sub> = 0 V to V <sub>CC</sub>			10	μA	1
Operating current	I <sub>CC1</sub>	t <sub>RC</sub> = 120 ns			65	mA	2
	I <sub>CC2</sub>	t <sub>RC</sub> = 1 μs			50		
	I <sub>CC3</sub>	t <sub>RC</sub> = 120 ns			60	mA	3
	I <sub>CC4</sub>	t <sub>RC</sub> = 1 μs			45		
Standby current	I <sub>SB1</sub>	$\overline{CE} = V_{IH}$			3	mA	
	I <sub>SB2</sub>	$\overline{CE} = V_{CC} - 0.2 V$			100		μA
Input capacitance	C <sub>IN</sub>	f = 1 MHz			10	pF	
Output capacitance	C <sub>OUT</sub>	T <sub>A</sub> = 25°C			10	pF	

## NOTES:

- $\overline{CE}/\overline{OE} = V_{IH}$
- V<sub>IN</sub> = V<sub>IH</sub> or V<sub>IL</sub>,  $\overline{CE} = V_{IL}$ , outputs open
- V<sub>IN</sub> = (V<sub>CC</sub> – 0.2 V) or 0.2 V,  $\overline{CE} = 0.2 V$ , outputs open

**AC CHARACTERISTICS ( $V_{CC} = 5\text{ V} \pm 10\%$ ,  $T_A = 0\text{ to }+70^\circ\text{C}$ )**

PARAMETER	SYMBOL	MIN.	TYP.	MAX.	UNIT	NOTE
Read cycle time	$t_{RC}$	120			ns	
Address access time	$t_{AA}$			120	ns	
Chip enable access time	$t_{ACE}$			120	ns	
Output enable delay time	$t_{OE}$			60	ns	
Output hold time	$t_{OH}$	5			ns	
CE to output in High-Z	$t_{CHZ}$			60	ns	1
OE to output in High-Z	$t_{OHZ}$			60	ns	

**NOTE:**

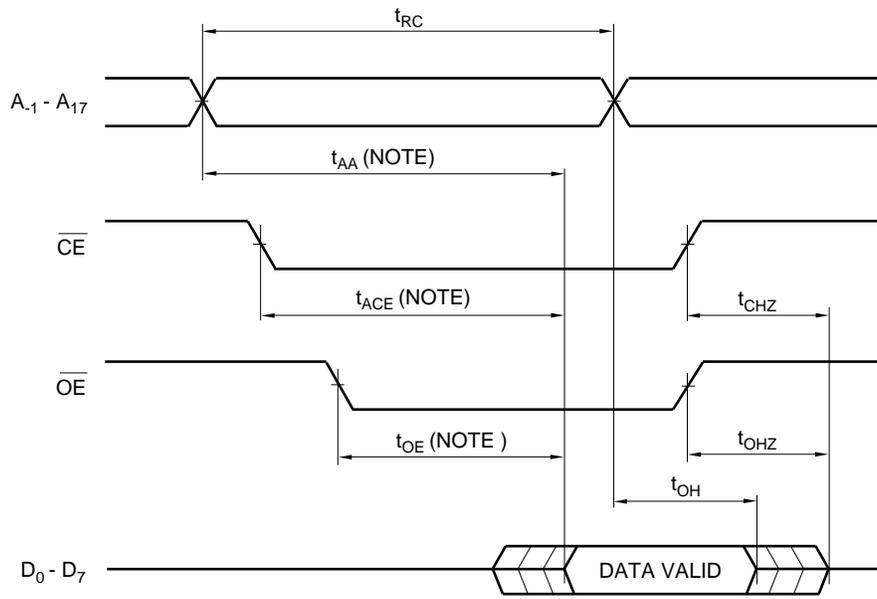
1. This is the time required for the outputs to become high-impedance.

**AC TEST CONDITIONS**

PARAMETER	RATING
Input voltage amplitude	0.4 V to 2.6 V
Input rise/fall time	10 ns
Input/output reference level	1.5 V
Output load condition	1TTL + 100 pF

**CAUTION**

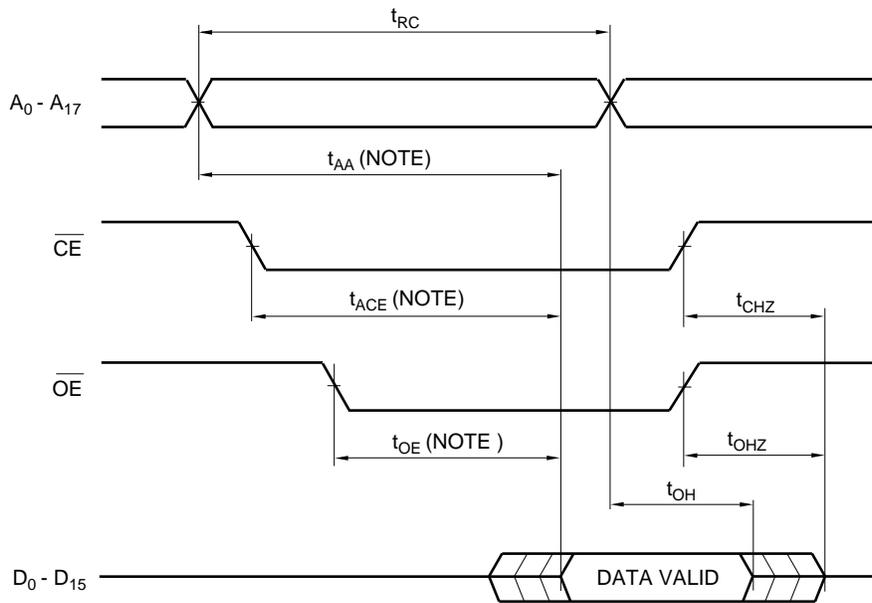
To stabilize the power supply, it is recommended that a high-frequency bypass capacitor be connected between the  $V_{CC}$  pin and the GND pin.



**NOTE:** The output data becomes valid when the last intervals,  $t_{AA}$ ,  $t_{ACE}$ , or  $t_{OE}$ , have concluded.

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**Figure 4. Byte Mode ( $\overline{BYTE} = V_{IL}$ )**

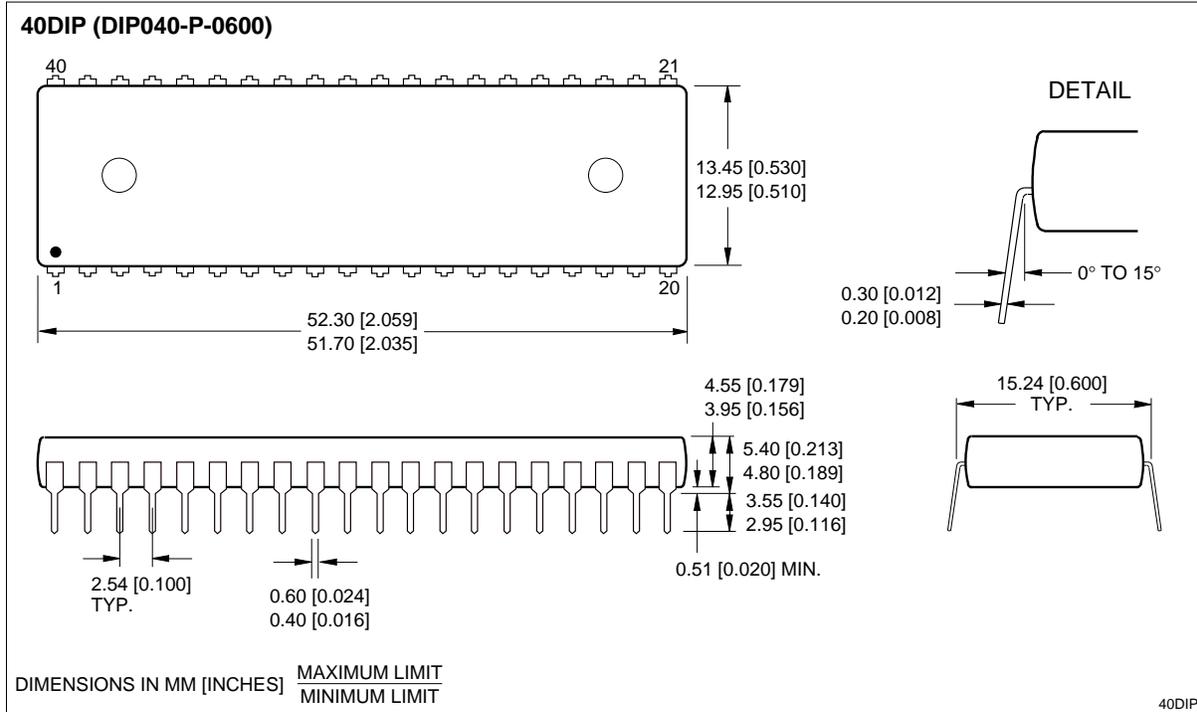


**NOTE:** The output data becomes valid when the last intervals,  $t_{AA}$ ,  $t_{ACE}$ , or  $t_{OE}$ , have concluded.

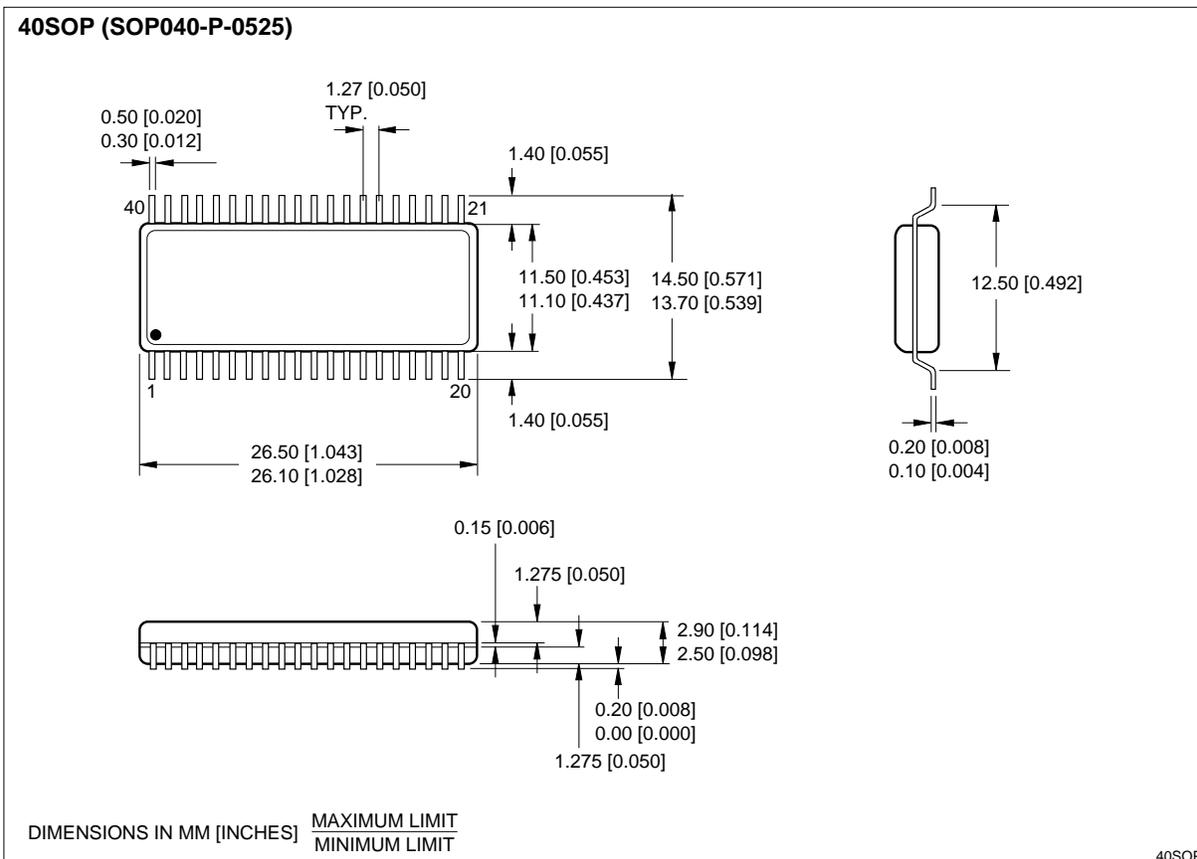
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**Figure 5. Word Mode ( $\overline{BYTE} = V_{IH}$ )**

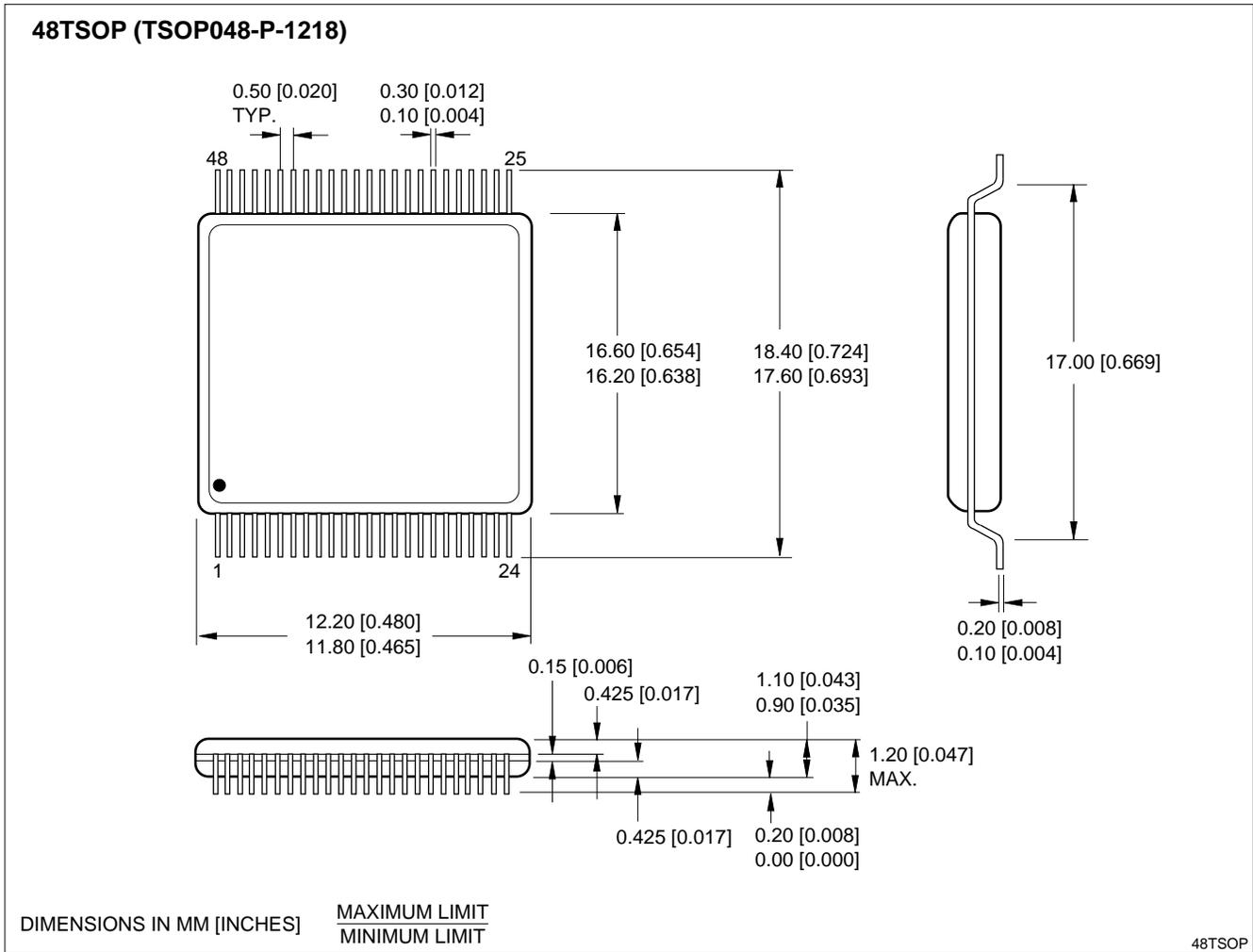
PACKAGE DIAGRAMS



40-pin, 600-mil DIP



40-pin, 525-mil SOP



**48-pin, 12 × 18 mm<sup>2</sup> TSOP (Type I)**

**ORDERING INFORMATION**

